IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved und international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mt	g Informat	ion		
upplier	Information													
Company r	name*	Company ur	Company unique ID			Unique ID Authority				Response Date*				
onsemi											2024-05-09			
Contact Na	nme		Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-E	nv-Stewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			F	Phone - Representative*			Email - Representative*					
Product-E	nv-Stewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number	Mfr Item	Number Mfr Item Name				Effective Date	ective Date		Ianufacturing Site	7	Veight*	UOM	Unit Type
	ECH8667-TL-H PCH+PCH 4V DI		PCH+PCH 4V DRI	IVE SERIES		2024-05-09 CNG		NG	1	9.18	mg	Each		
	eturing Process Inform		erminal Base	Alloy	STD-020 MS	. Pating	Peak Proce	ess Rody Te	emperatur	e Max Time at Peak	Temperati	ire Numb	per of Reflow Cyo	
		CU Alloy 1		31D-020 MS	L Kanng	Peak Process Body Temp			30			ber of Reflow Cyt	Lies	
omments	contains Di		C Andy	1			200		IC	130	secono	10 0		
	aximum time at peak tempera	turo durina col	doring is 10.	30 seconds										
	nformation regarding materia													

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.32	mg	Supplier	Silicon (Si)	7440-21-3		1.32	mg
Die Attach Solder	1.18	mg	Supplier	Silver (Ag)	7440-22-4		0.0295	mg
			A	Lead (Pb)	7439-92-1	7a	1.0915	mg
			Supplier	Tin (Sn)	7440-31-5		0.059	mg
Lead Frame	8.66	mg	Supplier	Silver (Ag)	7440-22-4		0.1048	mg
			Supplier	Tin (Sn)	7440-31-5		0.0121	mg
			Supplier	Copper (Cu)	7440-50-8		8.5431	mg
Mold Compound-Black	7.87	mg		Epoxy Phenol Resin	proprietary data		0.2991	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0787	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.787	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.509	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		1.1805	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0157	mg
Plating	0.14	mg	В	Bismuth (Bi)	7440-69-9		0.0008	mg
			Supplier	Tin (Sn)	7440-31-5		0.1392	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg